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PREPARED BY: DATE:		SPEC No./ BD-94097
D. Fujimara (Cct. 21, 199	SHARP	ISSUE / October 20, 1994
APPROVED BY: DATE:		PAGE 8 Pagest 1
WA CONTRACT	ELECTRONIC COMPONENTS GROUP SHARP CORPORATION	REPRESENTATIVE DIVISION
1.1. manaka bet. 21, 1994		OPTO-ELECTRONIC
	SPECIFICATION	DEVICES DIV.
	/ICE SPECIFICATION FOR	
	SOLID STATE RELAY	
MO	DEL No. S202T02	
1. These specification	on sheets include the contents under the copy	right of Sharp Corporation ("Sharp").
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	nstructions mentioned below for actual use of responsibility for damage caused by improper	
	s designed for general electronic equipment.	
• Computer	f this device are as follows; • • OA equipment • Telecommunication eq	uipment (Terminal)
1	g equipment • Tooling machine . AV equip	-
	proper stepa in order to maintain reliability an he uses mentioned below which require high re	
	erning control and safety of a vehicle (air plane	
• Traffic sig	nal \cdot Gas leak detection breaker \cdot Fire box	and burglar alarm box
L	ety equipment, etc.	
	t use for the uses mentioned below which requ upment •Telecommunication equipment (
	ontrol equipment • Medical equipment	
devices for any	P representative of sales office in advance when applications other than those applications for g	
recommend by S	SHAKP at (1).	
	DATE	red J. Matauna
CUSTOMERS APPRO	OVAL PRESEN BY	TED T ANT
DATE		Matsumura, partment General Mamger of
	———— Eng	gineering Dept. ,11 o-Electronic Devices Div.
BY		ECOM Group
	SHA	ARP CORPORATION

1. Application

This specification applies to the outline and characteristics of SIP type Solid State Relay (SSR), Model No. S202T02 (Apply line voltage 200V to 265V AC).

2. Outline

- 2.1 Refer to the attached drawing No. S3D94030.
- 2.2 (1) Trade mark (2) Model No. and (3) Lot symbol shall be indicated on the surface.
- 3. **Ratings** and characteristics : Refer to the attached sheet, Page 3 to 5.
 - 3.1 Absolute maximum ratings
 - 3.2 Electrical characteristics
- 4. Reliability

Refer to the attached sheet, Page 6, 7.

5. Incoming inspection

Refer to the attached sheet, Page 7.

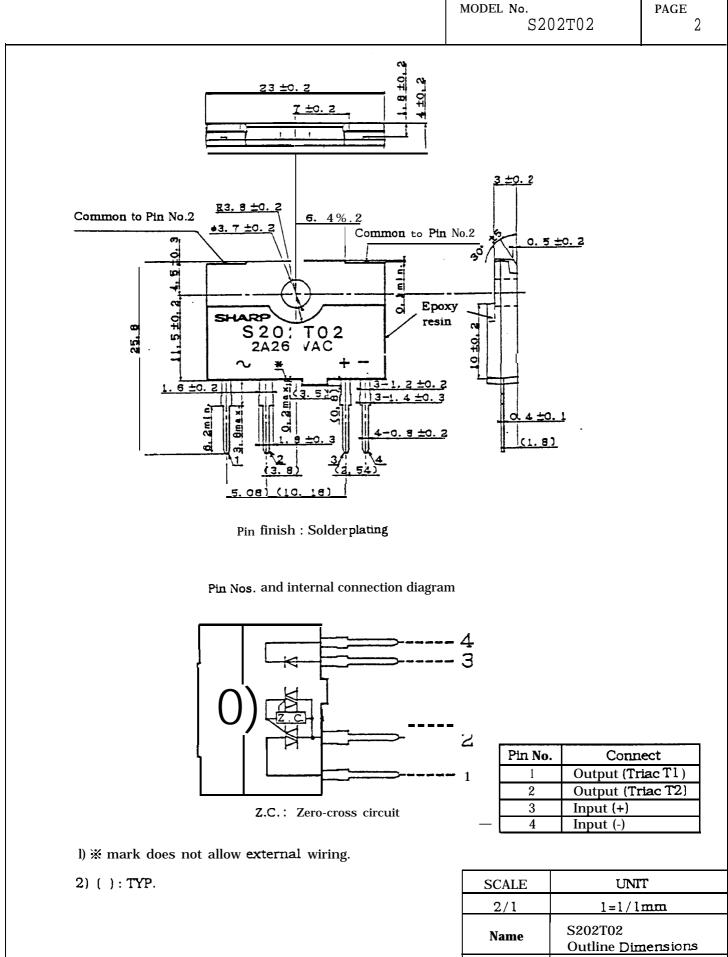
- 6. Supplements
 - 6.1 UL, CSA under preparation,
 - 6.2 This product is not designed against irradiation.

This product \mathbf{is} assembled with electrical input and output.

This product incorporates non-coherent light emitting diode.

7. Notes

Refer to the attached sheet, Page 8.



Drawing No.

S3D94030

3.1 Absolute maximum ratings

Ta=25°C

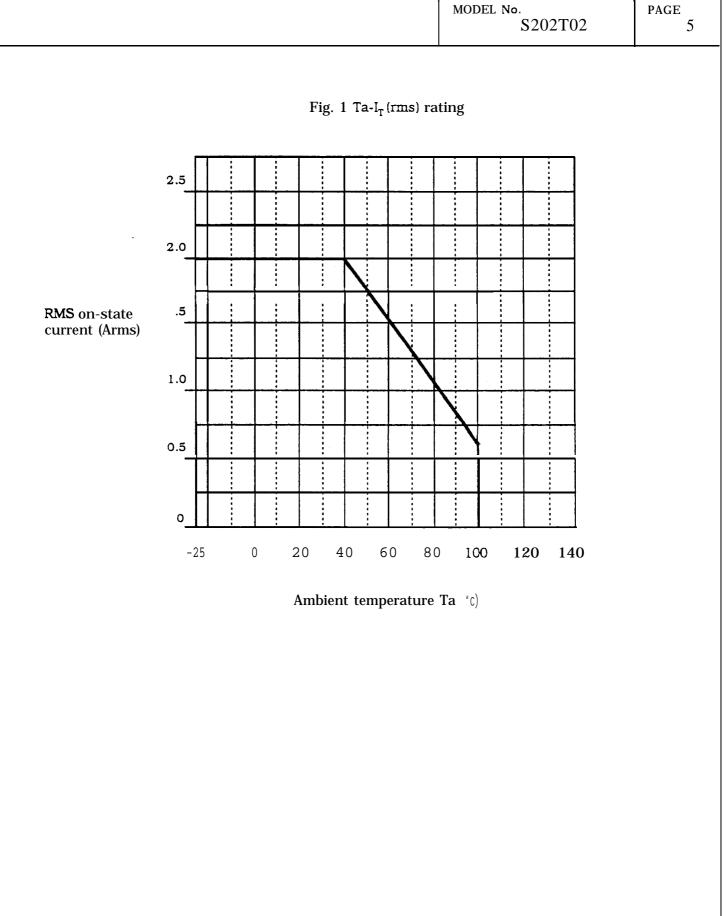
	Parameter	Symbol	Rating	Unit	Conditions
	Forward current	L _F	50	mA	
Input	Reverse voltage	V _R	6	V	
	RMS on-state current	L _T	2	Arms	Refer to the Fig. 1
-	Peak one cycle surge current	Isurge	20	A	60Hz sine wave Tj=25 °C start
output	Repetitive peak off- state voltage	V _{DRM}	600	v	
-	Non-repetitive peak off-state voltage	V _{DSM}	600	v	
	Critical rate of rise of on-state current	dI _T /dt	40	A/μs	
	Operating frequency	f	45 to 65	Hz	
0	perating temperature	Topr	-25 to +100	°	
S	torage temperature	Tstg	-30 to 125	ۍ ا	
Isolation voltage (*1)		Viso	3.0	kVrms	AC 60Hz, For 1 min RH=40 to 60%
Soldering temperature		Tsol	260	r	For 10 seconds

- (*1) Isolation voltage measuring method
 - (1) Dielectric withstand tester, with zero-cross circuit shall be used.
 - (21 The wave form of applied voltage shall be sine wave.
 - (3) It shall be applied voltage between input and output. (Inputs and outputs shall be short-circuited respectively)

3.2 Electrical characteristics

							Ta=25°C
	Parameter	symbol	MIN.	TYP.	MAX.	unit	Conditions
Innut	Forward voltage	V _F	-	1.2	1.4	v	I _F =20mA
Input	Reverse current	I _R	-	-	104	Α	V _R =3V
	Repetitive peak off-state current	I _{drm}			10-4	А	V _D =V _{DRM}
	On-state voltage	VT	-	-	1.7	Vrms	L _T =2Arms, R load, I _F =20mA
output	Holding current	I _H	-	-	25	mA	
	Critical rate of rise of off-state voltage	dv /dt	30	-	-	V/µs	$V_{D} = 2 / 3V_{DRM}$
	Commutation critical rate of rise of off- state voltage	(dv/dt)c	4	-	-	V/µs	Tj=125°C, V _D =400V dIt/dt=- 1.0A/ms
	Minimum trigger current	I _{FT}	-	-	8	mA	$V_{\rm D} = 6 \mathrm{V},$ $R_{\rm L} = 30 \Omega$
Transfer	Zero-cross voltage	Vox	-	-	35	v	I _F =8mA
charac - teris- tics	Isolation resistance	Riso	1010	-	-	Ω	DC500V RH=40 to 60%
	Turn on time	t _{ON}			10	ms	AC50Hz
	Turn off time	t _{off}			10	ms	AC50Hz

Ta=25°C



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4. Reliability

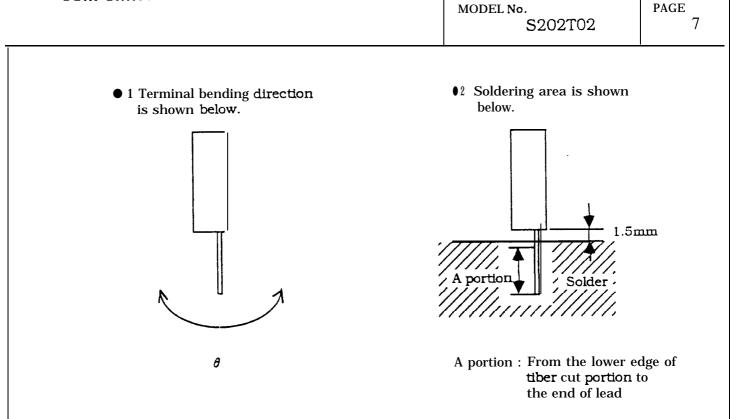
The reliability of products shall be satisfied with items listed below.

Confidence level: 90% LTPD : 10% / 20%

Test Items	Test Conditions	Judgement Criteria	Samples (n) Defective (C)
Temperature cycling	1 cycle -30"C to 125 C (30min.) (30min.) 20 cycles test	(1) Forward voltage:	n=22, C=O
High temp. high humidity storage	+60°C , 90%RH, 500h	I±5% or l ess (2) Reverse current:	n=22, C=O
High temp. storage	+125°C, 1000h	USLX2 or less	n=22, C=O
Low temp. storage	-30°C, 1000h	(3) Repetitive peak off-state current:	n=22, C=O
Intermittent operation	AC200V, 2Arms, Ta=25±3°C For 1min. ON, OFF, 500h	USLX2 or less	n.22, C=O
Vibration	200m/s ² 100 to 2000Hz/4min. 4times /X, Y, Z direction	(4) On-state voltage: USLX 1.2 or less	n=11, C=0
Terminal strength (Bending)	The first bending test is to put back into the original shape after the terminal bent 90" by a 5N load. The second bending test is to do the same but opposite direction. These two tests shall be performed.• 1	 (5) Minimum trigger current: USLX 1.2 or less (6) Isolation resist- ante, Isolation voltage: 	n=11, C=O
Terminal strength (Tension)	Weight : 10N 30s / terminal direction	Within the value Ofspec.	n=11, C=0
Soldering heat	260℃, 5s Up to 1 .5mm from resin portion ● 2		n=11, C=O
Solderability	230±5℃,5±0.5s Use rogin flux. ● 2	Solder shall adhere at the area or 95% or more of A portion	n=11, C=O

USL : Max. specification values

I : Initial values



5. Incoming inspection

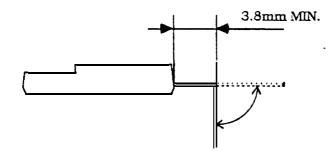
A single sampling plan, normal inspection level II based on MIL-STD- 105D is applied. The AQL according to the inspection items **are** shown below.

Defect	Inspection items	AQL(%)	Judgement criteria
Major defect	Electrical characteristics Unreadable marking Open, short	0.10	Depend on the specification
Minor defect	Appearance Dimensions	0.40	

Inspection items of electrical characteristics : V_{F} , I_{R} , I_{DRM} , V_{T} , I_{H} , I_{FT} , Vox, Viso, Riso

7. Notes

- (1 The LED chip used in the input side of Solid State Relay generally decreases the light emission power after long operation time. The amount of light emission power decrease depends on the ambient temp. and the applied current. (50%/5years) Please decide I_F value as 2 times of the Maximum value of the Minimum triggering current at circuit design.
- (2) Please make sure that surge absorption circuit and dv/dt control circuit are provided for protection of element. In general, we recommend that both CR circuit and varistor be used in conjunction. Watch for faulty operation that may be caused by leakage current that runs through the CR circuit.
- (3) Current value of the load shall be holded within the range of **derating** curve. **Install** an optional heat sink as required.
- (4) If it is **necessary** to bend **terminal** pins, please bend them **3.8mm** or more away **from** base of terminal pins to prevent mechanical stress between base of **terminal** pins and **resin** of mold.



(5) Some have a built-in rectifier such as diode, etc. as part of the electromagnetic counter or solenoid specified for use on AC. If this is the bee, check out properly the wave form of the load current. If it is a rectangular wave as it may become, the SSR will not tum OFF.

(6) Cleaning conditions:

1) Solvent cleaning:	Solvent temperature 45°C or less , Immersion 3min. or less
2) Ultrasonic cleaning :	The affect to device by ultrasonic cleaning is different by cleaning bath size, ultrasonic power output, cleaning time, PWB size or device mounting condition etc. Please test it in actual using condition and confirm that doesn't occur any defect before starting the ultrasonic cleaning.
3) The cleaning shall be	carried out with solvent below.
Solvent:	Ethyl alcohol, Methyl alcohol, Isopropyl alcohol
	Freon TE • TF, Daiflon-solvent S3-E, S3-MC
Please refrain from usin	g Choloro Fluoro Carbon type solvent to clean

devices as much as possible since it is internationally restricted to protect the ozonosphere. Before you use alternative solvent you are requested to confirm that it does not damage package resin.